Techor System Modules Comparisons

Product Name	SOM2416: S3C2416(ARM926EJ)	SOMA310: PXA310	SOM3530: OMAP3530(600/720MHz	SOM6410:S3C6410(ARM1176JZF-S)	SOM3517:TI AM3517(Coretex-A8)	Rev: 20101130 SOMV210: S5PV210(Cortex-A8)	http://www.techor.com SOM168: PXA168/PXA166(Marvell AR
			Cortex-A8 + TMS320C64x+)			5	V5TE Sheeva)
Picture			The same of the sa				
Brand Price:	TECHOR ¥500	TECHOR ¥0	TECHOR ¥800	TECHOR ¥700	TECHOR Y0	TECHOR ¥0	TECHOR ¥0
Gross weight:	8gram	7gram	10gram	8gram	11gram	15gram	11gram
Model Form actor	Model II (40x40mm/120pin/1.27mm pitch) ,Model I (40x40mm/74pin/2.0mm pitch)	Model-V(SODIMM 200)	Model II(40x40mm/120pin/1.27mm pitch)		Model III(40x40mm/152pin/1.0mm pitch)	Model- IV(48x48mm/164pin/1.1mm pitch)	Model II(40x40mm/120pin/1.27m pitch)
mensions(LxWx),mm	40x40mm, 4mm thickness	67.6 x 30 x 8 mm	40x40x3mm	40x40mm, 3mm thickness	40x40mm, 3mm thickness	48x48mm, thickness 3.5mm	40x40mm, 4mm thicknes
Processor(Core)	Samsung S3C2416(ARM926EJ)- 65nm	Marvell PXA310(XScale ARMv5TE)	TI OMAP35xx(Cortex-A8 + TMS320C64x+)	Samsung S3C6410(ARM1176JZF-S)	TI AM3517(Cortex-A8)	Samsung S5PV210(Cortex-A8)	Marvell PXA16x(XScale)
Speed: ORE/SDRAM	400MHz(cpu)/266M(DDR2 SDRAM)	624MHz / 208MHz	600MHz Cortex-A8 / 430MHz TMS320C64x+ DSP Core L1/SRAM: 112 KB (DSP),32 KB	667MHz(FCLK)/266MHz(HCLK)/67MH z(PCLK)	500MHz Coretex-A8/DDR2 266MHz	1G HCKH	800MHz/1G
-Cache/ D- ache, L2	16KB/16KB	32KB/32KB,WMMX2	(ARM Cortex-A8) / L2/SRAM: 96 KB (DSP),256 KB (ARM Cortex-A8)	16KB/16KB I/D Cache and 16KB/16KB I/D TCM	L1: ARM:16 KB I-Cache/16 kB D-Cache; L2: 256KB		L1/L2 cache
Floating oint/MAC Internal SRAM	NC 64KB for internal SRAM Buffer	No?(To Be Determined) 2*128K internal SRAM	64KB RAM	VFP coprocessor support	64KB	Yes	
SDRAM	64MB, 16-Bit DDR2	64/128MB DDR,16bit	128MB mDDR; 256MB optional	128MB mDDR, 32bit; data bus with 266Mbs/pin double data rate	standard 256MB, 512MB optional	512MB DDR2, 1G optional	128MB
land Flash	128MB/8-Bit/SLC,256MB/8- Bit/SLC,512MB/8-	256MB/8-Bit/SLC	128MB,512MB,256MB	256MB/8bit/SLC,512MB/8bit/SLC,128	256MB/8bit/SLC	256MB/8bit/SLC	256MB/8bit/SLC
ixpansion Bus	Bit/SLC,1024MB/8-Bit/MLC 7-Bit Address/8-Bit Data Local	16bit Data / 20bit Address	8bit Data,8 bit Address	MB/8bit/SLC 8-Bit Address/8-Bit Data Local Bus	10bit Address/16bit Data Local	8bit Address/8bit Data Local Bus	Yes
Boot Options	On board NAND / Off board SD/MMC	On Module Nand/Off module SD/MMC card	SD/MMC boot&Nand boot	On board NAND / Off board SD/MMC		On board NAND / Off board SD/MMC	
UART	4-ch: Uart0/1: 4- wire(TX/RX/RTS/CTS); uart2/3: 2-	3 UART ports, 16550 compatible, max 921 kbps	3-CH, 4 wires(TXD,RXD,nRTS,nCTS)	4-ch: Uart0/1: 4- wire(TX/RX/RTS/CTS);uart2/3: 2-	4-ch: Uart0/1/2: 4- wire(TX/RX/RTS/CTS); uart3: 2-	4-ch: Uart0/1: 4- wire(TX/RX/RTS/CTS);uart2/3: 2-	3-ch
Slow IrDA/ Fast DA	wire(TX/RX) IrDA 1.0, multiplex with UARTs	1 SIR	IrDA/CIR,mux with third UART	FIR up to 4Mbps, IrDA 1.1, multiplex with UART	wire(TX/RX)	wire(TX/RX) mux with uart	mux with uart
SPI, # of Chip elects	1-CH high speed SPI, protocol version 2.11	Yes	4-ch of McSPI	1-ch	1-ch	1-ch, Master/Slave, High-Speed	
2C Bus	1-CH Multi-Master IIC-Bus	Yes	1-ch, Master/Slave, High-Speed	1-ch,Multi-Master	1-ch	Yes	I2C(TWSI), One- Wire(OWSI)
imer/PWM	3-CH 16bit 2-CH.SDIO 1.0/HS-MMC 4.2/SD	>2	5-ch 32bit Timers, with 1 PWM output	5-ch 32bit Timers, with 1 PWM output		Yes	
b/MMC terface	Host 2.0/SD Memory Card Protocol 2.1/CE-ATA	2 SDIO	1-ch 8bit SD/MMC	2-ch MMC4.0/SDMC2.0/SDIO 1.0	2-ch SC/MMC	2-ch MMC4.0/SDMC2.0/SDIO 1.0	2-ch SD/MMC
ISB Host Ports	1-CH of OHCI 1.0 USB Host,Compatible USB 1.1	2-ch	1-ch USB 2.0 with OTG mux with device	1-ch, OHCI 1.0/USB 1.1	1-ch USB 2.0 High Speed Host	1-ch USB 2.0 Host	1-ch USB 2.0 Host
JSB Device Port	1-CH USB 2.0 Spec USB device, 9 Endpoints	1(OTG)	1-ch USB 2.0 with OTG mux with host	1-ch USB OTG 2.0 High Speed	1-ch USB 2.0 HS OTG with PHY	1-ch USB 2.0 with OTG	USB 2.0 OTG 10/100MB high
thernet terface	10/100MB high performance Ethernet(LAN9220/LAN9221)	No	10/100Mhz high performance Ethernet(Lan9220/1)	10/100MB high performance Ethernet(LAN9220/LAN9221)	10/100M Ethernet(RMII)	10/100MB high performance Ethernet(LAN9220/LAN9221)	performance Ethernet(LAN9220/LAN922
Audio I/F	I2S of WM8731 codec, Line In/Line Out/Microphone I/F	Line In/Line Out/Mic	Stero Out/Mic	12S of WM8731 codec, Line In/Line Out/Mic	IIS codec, Line In/Line Out/MIC	IIS codec, Line In/Line Out/MIC	Stero In/Out/Mic
CMCIA/Compact ash	No	No	No		No	No	18 bit, typical
CD I/F esolution,Depth)	Typically 800x600,16bit/18bit	800x600,18bit	Typical 1024x768,800x600 etc.	Max 1024x768, 18bit	Typical 1024x768, 24bit	Typical 1024x768,800x600 etc.	800x600,1024x768,up to WUXGA
erformance(Res@s)	(To Be Determined)	(To Be Determined)	1920x1024 of H.264 decoding @ 25fps Video Hardware Accelerators/	Codec H.264 up to 30fps@SD		Codec H.264 up to 30fps@SD	WMMX2
PD/3D Graphics	2D Graphics Accelerator Engine	3D Accelerator	POWERVR SGX Graphics Accelerator, OpenGL ES2.0	2D/3D Graphics Accelerator,OpenGL ES 2.0,D3D Mobile; Multi Format Codec	POWERVR SGX, 2D/3D Graphics Engine	Yes	technology, Graphics acceleration
/ideo/Camera put	No	8/10-Bit YUV/RGB	8bit Camera VIP port	ITU-R 601/ITU-R 656,8bit,up to 4096x4096 in YCbCr 4:2:2 format	8bit Camera I/F	ITU-R 601/ITU-R 656,8bit,up to 4096x4096 in YCbCr 4:2:2 format	ITU-656 camera input
SPIO Other Features	10+~30+ Channels	10+	20+ ch (Muxed) 1-ch 1-Wire(HDQ)	30+ ch,mux	40+ ch,mux 3.3V I/O Voltage	30+ ch,mux	
vailability	Samples/Small Qty/Large Qty	Samples/Small Qty/Mass Qty/Now	Samples/Small Qty	Samples/Small Qty Now	Samples in Dec 2010	Samples in Dec 2010	Samples in Dec 2010
Can Bus Temperature ange	NC 0~70 Degree	No -0 to +70 Degree	0~90 degree	No 0~70 degree, I/E Class optional	1-ch,HECC 0~90 degree, I/E Class optional	No 0~70 degree, I/E Class optional	
extended Emperature Otion	Available for MOQ 500	Available for MOQ 500	-40 to 105 degree on MOQ 500	Available on MOQ 500	-40 to 105 degree on MOQ 500	Yes	Yes
Power Ipply/Consumpti I	Single 3.1~3.6V / 0.1~1.0W depending on configuration and mode	Single 3.3~3.6V / 0.2~1.5W depending on configuration and mode	3.3V/1W	0.5W on full speed	3.3V/1W	3.3V/1W	3.3V/1W
ouch Panel entroller	4-wire,support Resistive Touch Panel	4-wire,support Resistive Touch Panel	4-wire, Resistive	4-wire, Resistive	4-wire, Resistive	4-wire, Resistive	
RoHS(lead-free) otion	Available for MOQ 500	Available for MOQ 500	Yes	Available on MOQ 500	Yes	Yes	Yes
TAG	Yes(bottom layer of test points) CPU internal, external backup	Yes	8pin test point on bottom layter	8pin test point on bottom layter CPU internal, external backup	8pin test point on bottom layter	8pin test point on bottom layter	Yes
RTC Flash Availability	battery input 64MB~4GB of Nand Flash	Yes, offboard battery backup 256MB of SLC Nand	Yes,Internal Battery Backup standard 128MB, 256MB/512MB	battery input 64MB~4GB of Nand Flash optional	Yes,CPU Internal 128MB~4GB on demand	Yes,CPU Internal 128MB~4GB on demand	Yes 128MB~4GB on demand
nterrupt Source	optional 12	5+	optional	3-ch External Interrupt Source		Yes	400 on demand
ADC/DAC	2-CH ADC	3-ch	2-ch ADC	4-ch ADC mux with Touch Panel Controller		Yes	
Vatchdog deo/HDMI/DVI	Yes,CPU Internal	CPU internal	2-ch 32-Bit WD	CPU internal 2-ch Composite Video Output	Yes CVBS Outpout	Yes CVBS Outpout	Yes
PU Variations	SC2416XH-40, 400MHz	CPU: Marvell XScale® ARM®	CUS package, 600MHz of Coretex-	S3C6410XH-66, 667MHz		S5PV210XH-A0, 1GHz	800MHz Sheeva
Vifi Extension	10, 10011112	PXA310(Monahans)	A8	30, 00/mil		802.11 b/g Marvrell 88W8686 WIFI I/F	PXA166(ARM V5TE) 802.11 b/g Marvrell 88W8686 WIFI I/F
						WIFI I/F S0MV210是一款世界上尺寸最小	OOWOOOD WIFI I/F
Brief:	4x4cm Tinv System Module based on Samsung S3C2416 400MHz ARM926EJ CPU, 64MB RAM/256MB 266 Flash, rich connectivity: Ethernet/Audio/IIC/4 UARTs/SPI/2 SDIOs/USB Host/device		TI OMAP35xx(Cortex-A8 + TMS320C64x+)based,集成Ethernet,音頻 codec.有丰富接口。 USB/Uart/SPI/IZC/LCD/Camera/SDMMC,128M B~512MB Flash和128MB~256MB Flash	Embedded computer, Embedded System Mod	TI_AM3517(Coretex-A8) System Module (compact:4x4cm,11g),with Ethernet/USB/Video Input Output/LC/SPI/Uart/TIC/MMC/Audio/CA N_bus, 3D_Accelerator	SOMVEIU是一条电子上个J服子 (4.8x4.8cm,3mmF)集成度最高(CPU外閉集 成Ethernet、音频Codec)的系统模块 (System Module)。专门面向手持终端设备 PPA、人机界面、自动售货机、广告机、 监控设备、通讯设备等设计的高性价比核 心板、该系统模块采用邮票孔式设计组 锅、可直接焊接在底板上,其特点是尺寸	TI AM3517 (Coretex-A8)
	(A. n. n.)			ule	(a, p. 72)	小, 功能全, 焊接方便, 功耗小, 性能稳定。	



















